



Greg Hemstreet
Manager, Processor Expert Software

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Agenda

- Introduction and Industry Trends
- Memory Organization and Operation
- Features and Capabilities
- Demo
 - DDR configuration using QorIQ Configuration Suite
 - DDR validation using DDRv plug-in to QCS

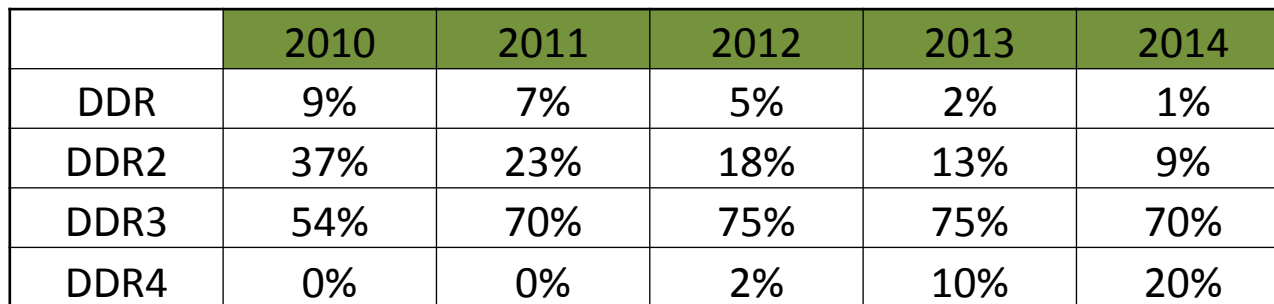
[illegible]

- Many customers are deploying and expect DDR3 support on their new product offerings, especially since the price cross-over point occurred in Q1 of 2010
- Since 2008, almost all Freescale networking devices offer DDR3 support
- Many of the QorIQ devices offer DDR3L support
- Freescale devices with DDR3/DDR3L support provide customers with higher performance memories at lower power-consumptions levels
- The first QorIQ device with DDR4 is expected by end of 2013 (T1040).

DDR – Major Vendors

- Supported by all major memory vendors





DDR SDRAM Highlights and Comparison

Feature/Category	DDR1	DDR2	DDR3
Package	TSOP	BGA only	BGA only
Densities	128Mb -1Gb	256Mb - 4Gb	512Mb -8Gb
Voltage	2.5V Core 2.5V I/O	1.8V Core 1.8V I/O	1.5V Core 1.5V I/O
I/O Signaling	SSTL_2	SSTL_18	SSTL_15
Internal Memory Banks	4	4 to 8	8
Data Rate	200-400 Mbps	400–800 Mbps	800–1600 Mbps
Termination	Motherboard termination to V_{TT} for all signals	On-die termination for data group. V_{TT} termination for address, command, and control	On-die termination for data group. V_{TT} termination for address, command, and control
Data Strokes	Single Ended	Differential or single	Differential

DDR SDRAM Highlights and Comparison (continued)

Feature/Category	DDR1	DDR2	DDR3
Burst Length	BL= 2, 4, 8 (2-bit prefetch)	BL= 4, 8 (4-bit prefetch)	BL= 8 (Burst chop 4) (8-bit prefetch)
CL/tRCD/tRP	15 ns each	15 ns each	12 ns each
Master Reset	No	No	Yes
ODT (On-die termination)	No	Yes	Yes
Driver Calibration	No	Off-Chip (OCD)	On-Chip with ZQ pin (ZQ cal)
Write Leveling	No	No	Yes

DDR SDRAM Highlights and Comparison

Feature/Category	DDR3	DDR4
Package	BGA only	BGA only
Densities	512Mb -8Gb	2Gb -16Gb
Voltage	1.5V Core 1.5V I/O	1.2V Core 1.2V I/O
Data I/O CMD, ADDR I/O	Center Tab Termination (CTT) CTT	Pseudo Open Drain (POD) CTT
Internal Memory Banks	8	16 for x4/x8 8 for x16
Data Rate	800–2133 Mbps	1600–3200 Mbps
VREF	VREFCA & VREFDQ external	VREFCA external VREFDQ internal , per DRAM
Data Strobes/Prefetch/Burst Length/Burst Type	Differential/8-bits/BC4, BL8/ Fixed, OTF	Same as DDR3
Additive/read/write Latency	0, CL-1, CL-2/ AL+CL/ AL +CWL	Same as DDR3

DDR SDRAM Highlights and Comparison (continued)

Feature/Category	DDR3	DDR4
CRC Data Bus	No	Yes
Boundary Scan/Connectivity test (TEN pin)	No	Yes
Bank Grouping	No	Yes
Data Bus Inversion (DBI_n pin)	No	Yes
Write Leveling / ZQ	Yes	Yes
ACT_n new pin & command	No	Yes
Low power Auto self-refresh	No	Yes

DDR3/DDR3L/DDR4 Power Saving

- DDR3 DRAM provides 25% power savings over DDR2
- DDR3L DRAM provides 15% power saving over DDR3
- DDR4 DRAM provides 37% power saving over DDR3L

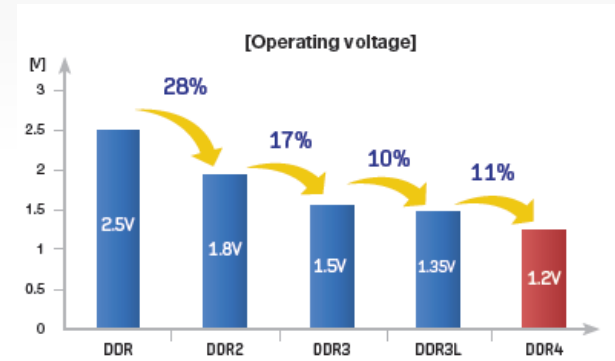


Figure 4. Reduced operating voltage requirements of DDR4 compared to DDR3L

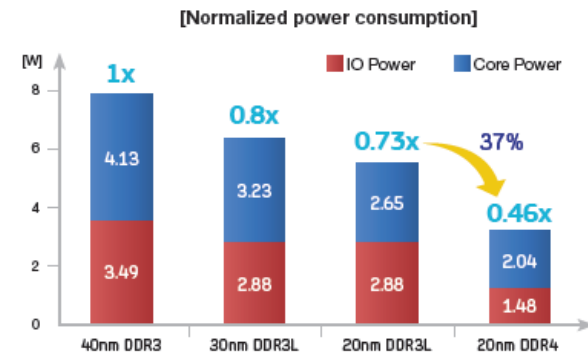


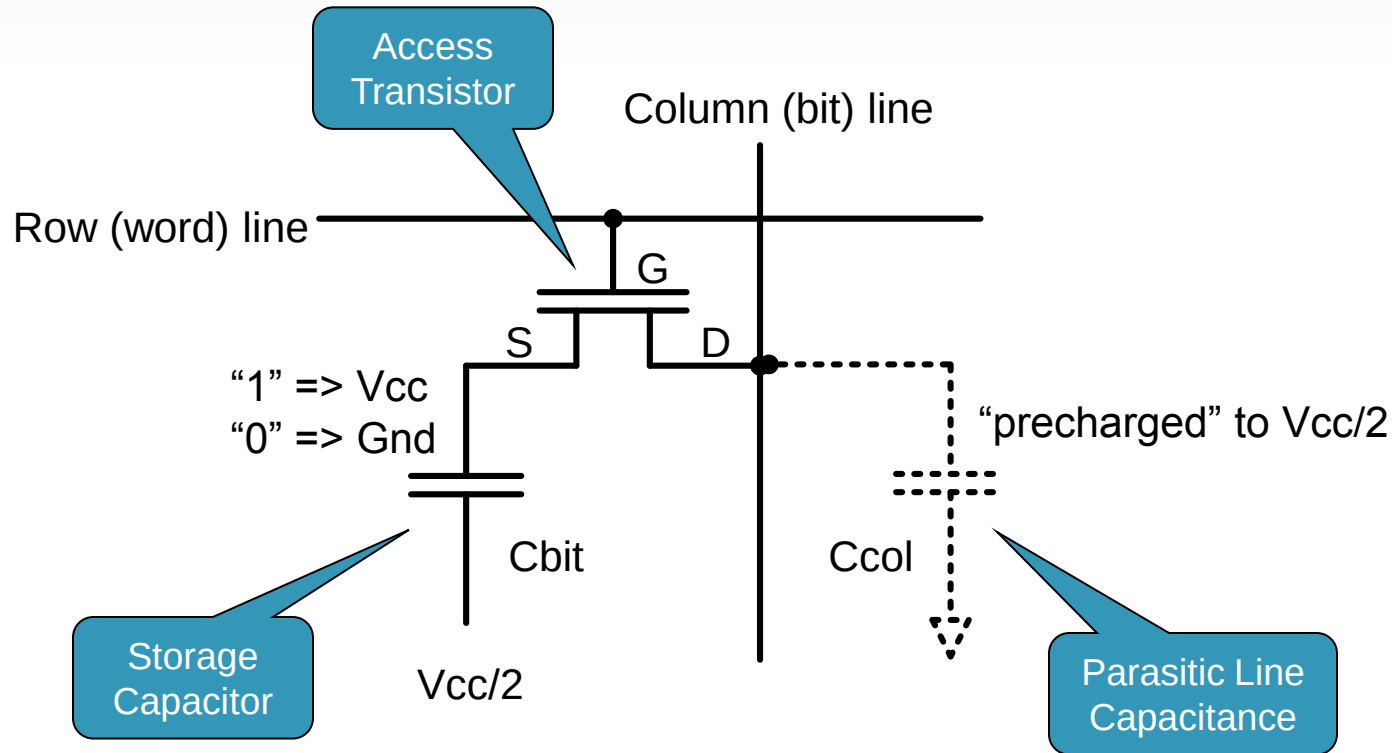
Figure 5. Reduced normalized power consumption requirements of DDR4 compared to DDR3L



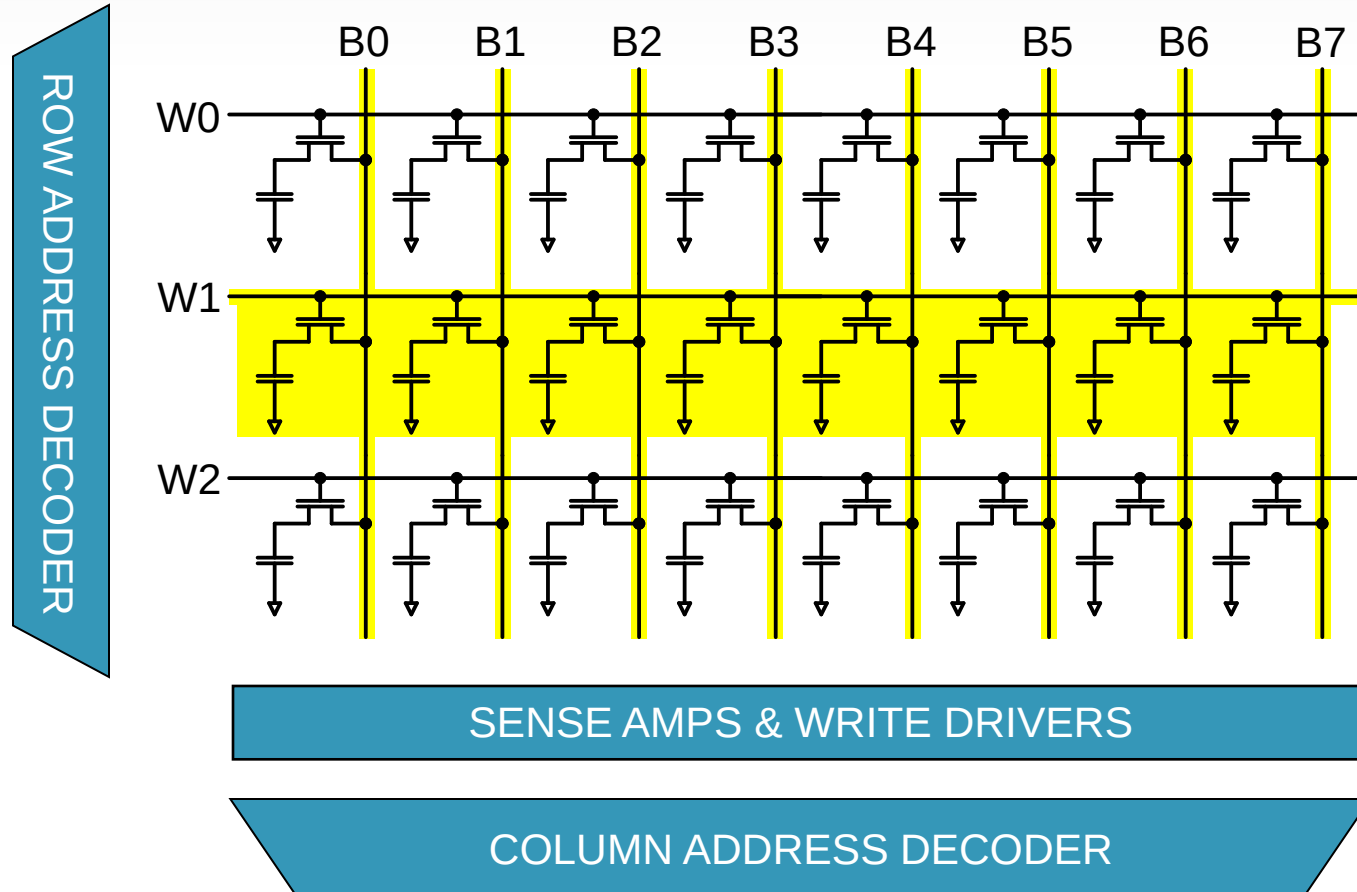


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Single Transistor Memory Cell

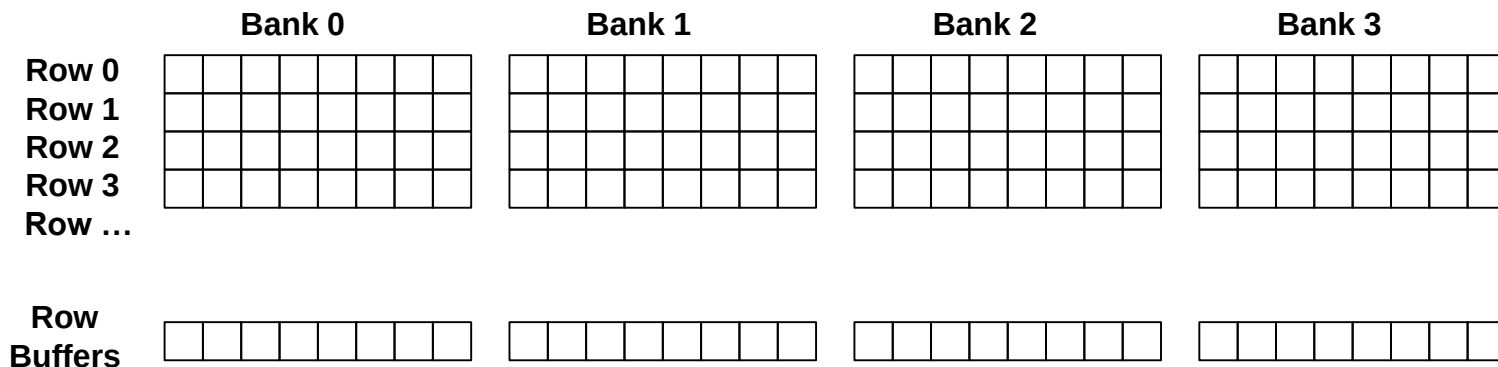


Memory Arrays



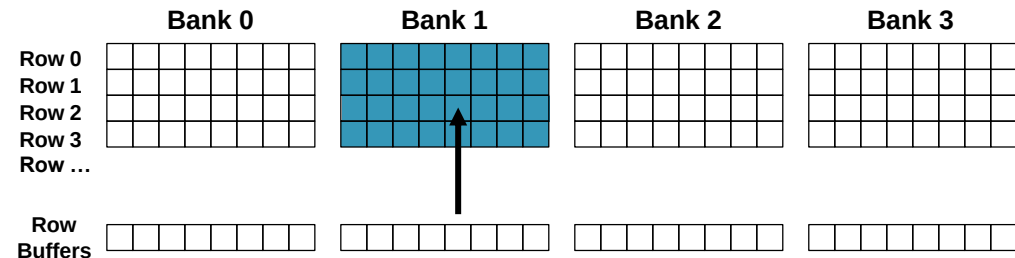
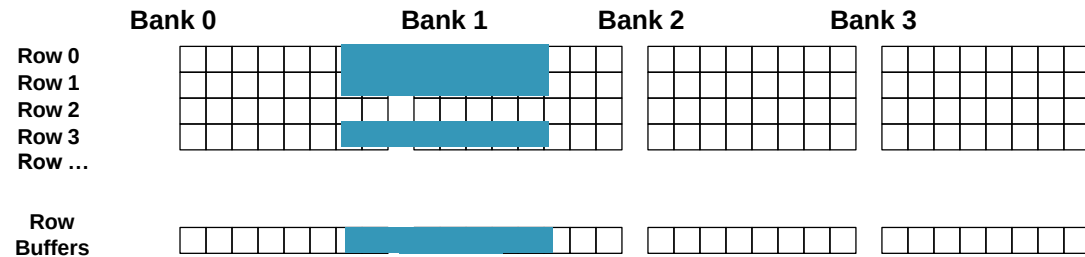
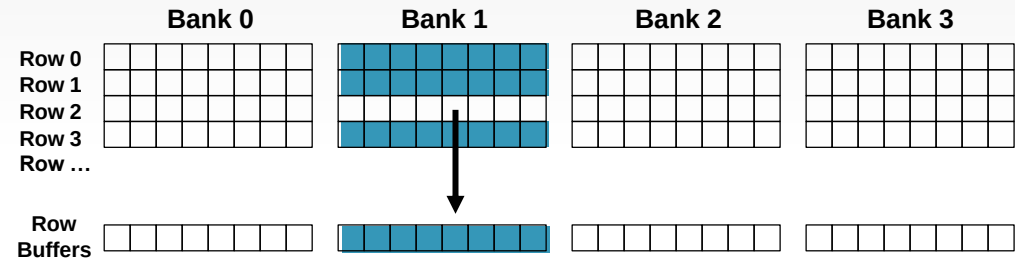
Internal Memory Banks

- Multiple arrays organized into banks
- Multiple banks per memory device
 - DDR1 – 4 banks, 2 bank address (BA) bits
 - DDR2 & DDR3 – 4 or 8 banks, 2 or 3 bank address (BA) bits
 - DDR4 -16 banks , with 4 banks in each of 4 bank groups
 - Can have one active row in each bank at any given time
- Concurrency
 - Can be opening or precharging a row in one bank while accessing another bank
- May be referred to as “internal”, “logical” or “sub-” banks



Memory Access

- A requested row is **ACTIVATED** and made accessible through the bank's row buffer
- **READ** and/or **WRITE** are issued to the active row
- The row is **PRECHARGED** and is no longer accessible through the bank's row buffer



QorIQ Family DDR Controllers

Features and Capabilities



DDR1/DDR2/DDR3/DDR3L Controller Features

- Supports most JEDEC standard x8, x16, x32 DDR1 & 2 & 3 devices
- Memory device densities from 64Mb – through 4Gb
- Data rates up to: 333 Mb/s for DDR1, 800 Mb/s for DDR2 and 1600 Mb/s DDR3
- Devices with 12-16 row address bits, 8-11 column address bits, 2-3 logical bank address bits
- Data mask signals for sub-doubleword writes
- Up to four physical banks (ranks / chip selects)
- Physical bank (rank) sizes up to 4GB, total memory up to 16GB per controller
- Physical bank interleaving between 2 or 4 chip selects
- Memory controller interleaving when more than 2 controllers are available
- Un-buffered or registered DIMMs

DDR1/DDR2/DDR3/DDR3L Controller Features (continued)

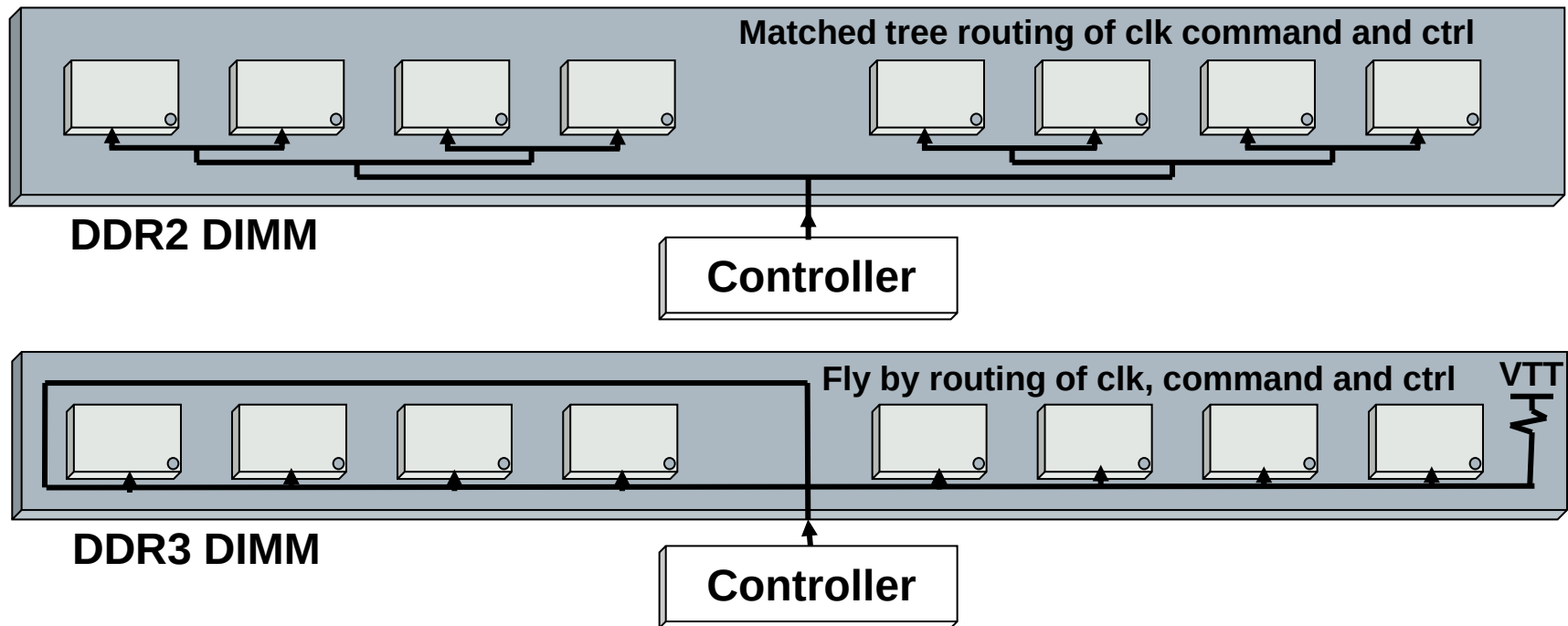
- Up to 32 open pages
 - Open row table
 - Amount of time rows stay open is programmable
- Auto-precharge, globally or by chip select
- Self-refresh
- Up to 8 posted refreshes
- Automatic or software-controlled memory device initialization
- ECC: 1-bit error correction, 2-bit error detection, detection of all errors within a nibble
- ECC error injection
- Read-modify-write for sub-doubleword writes when using ECC
- Automatic data initialization for ECC
- Dynamic power management

DDR2/DDR3/DDR3L Controller Additional Features

- Partial array self refresh
- Address and command parity for Registered DIMM
- Independent driver impedance setting for data, address/command, and clock
- Synchronous and Asynchronous clock-in option
- Write-leveling for DDR3
- Automatic CPO (operational)
- Asynchronous RESET for DDR3
- Automatic ZQ calibration for DDR3
- Fixed or On-the-Fly burst chop mode for DDR3
- Mirrored DIMM supported
- Many QorIQ devices offer full DDR3L support

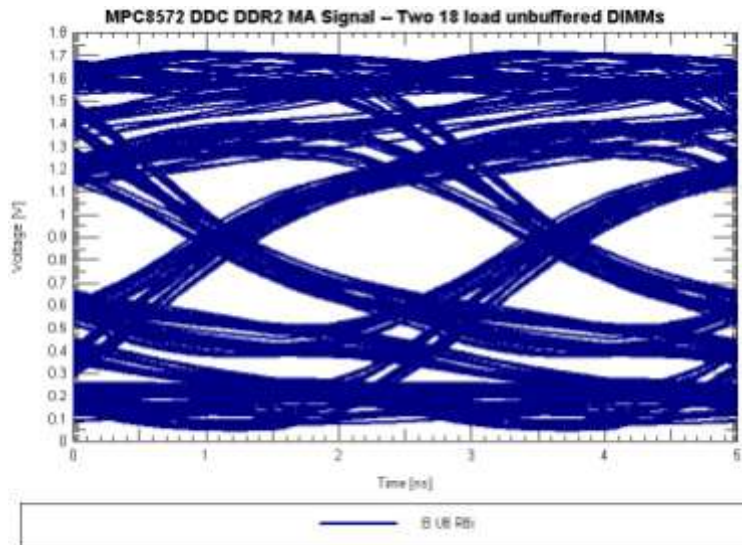
Fly-By Routing Topology

- Introduction of “fly-by” architecture
 - Address, command, control & clocks
 - Improved signal integrity...enabling higher speeds
 - On module termination

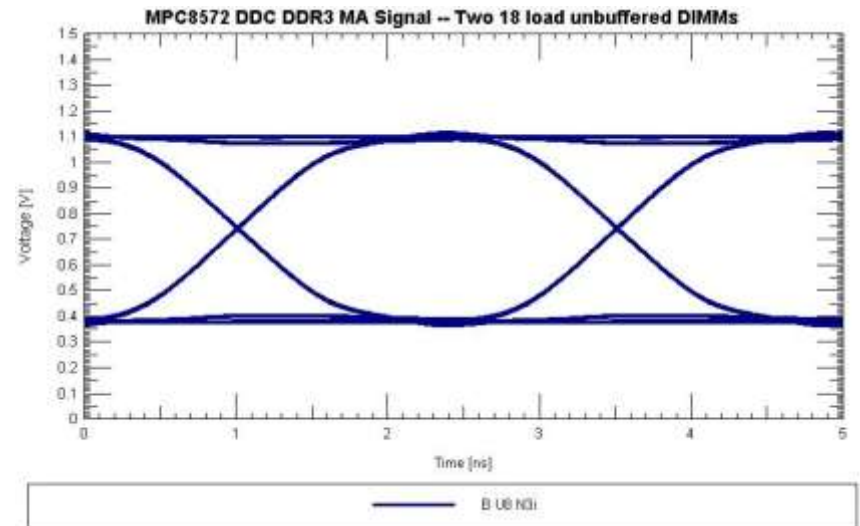


Fly-By Routing Improved SI

DDR2 Matched Tree Routing

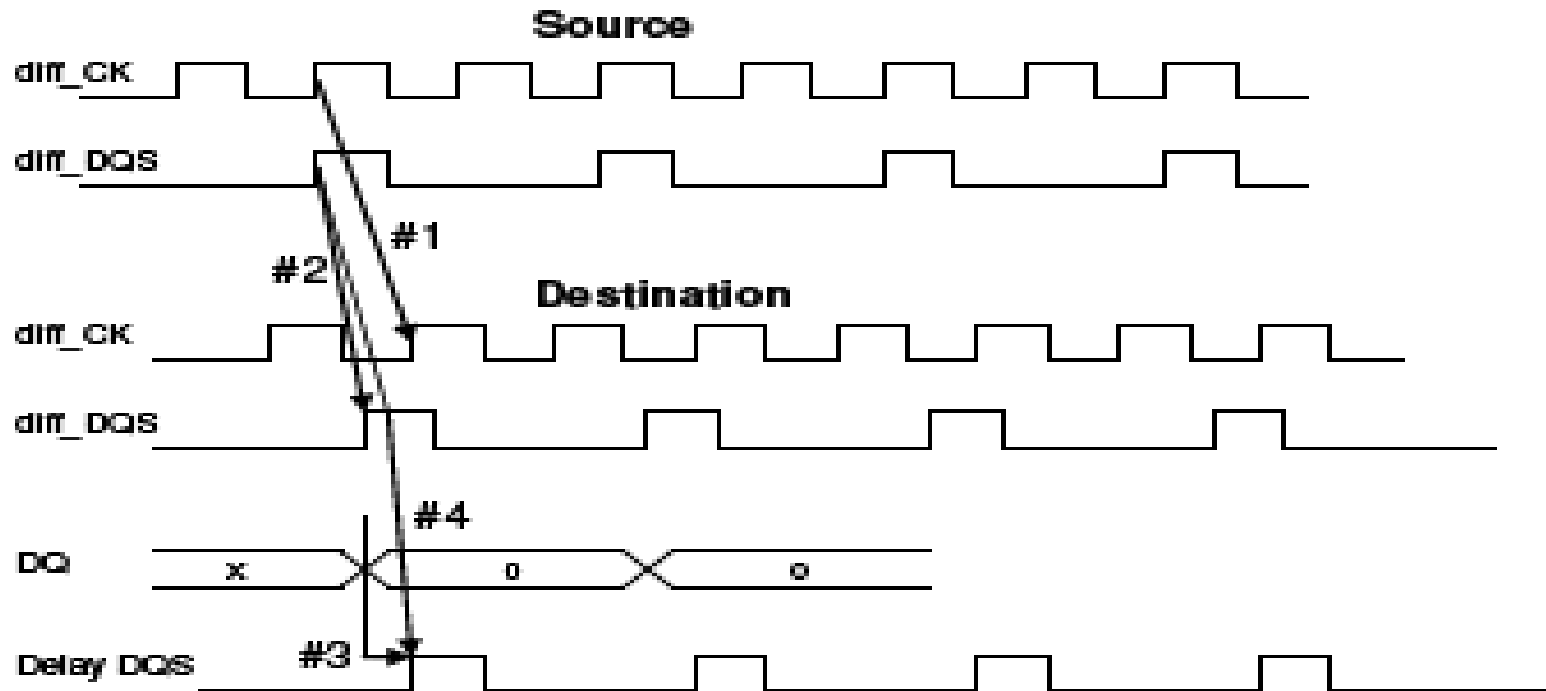


DDR3 Fly By Routing

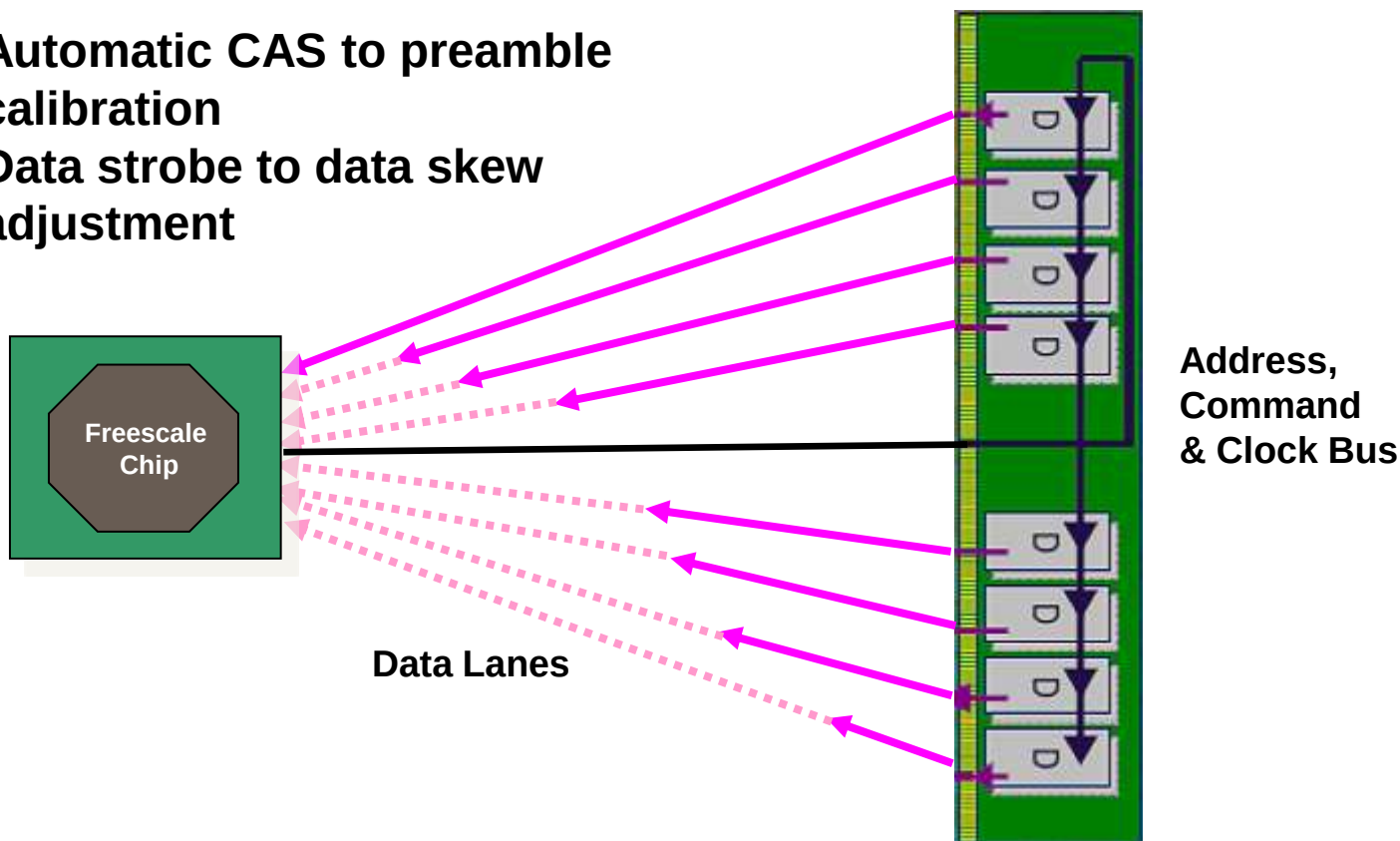


What Is Write Leveling

- During a write cycle, the skew between the clock and strobes is increased due to the fly-by topology. The write leveling will delay the strobe (and the corresponding data lanes) for each byte lane to reduce/compensate for this delay



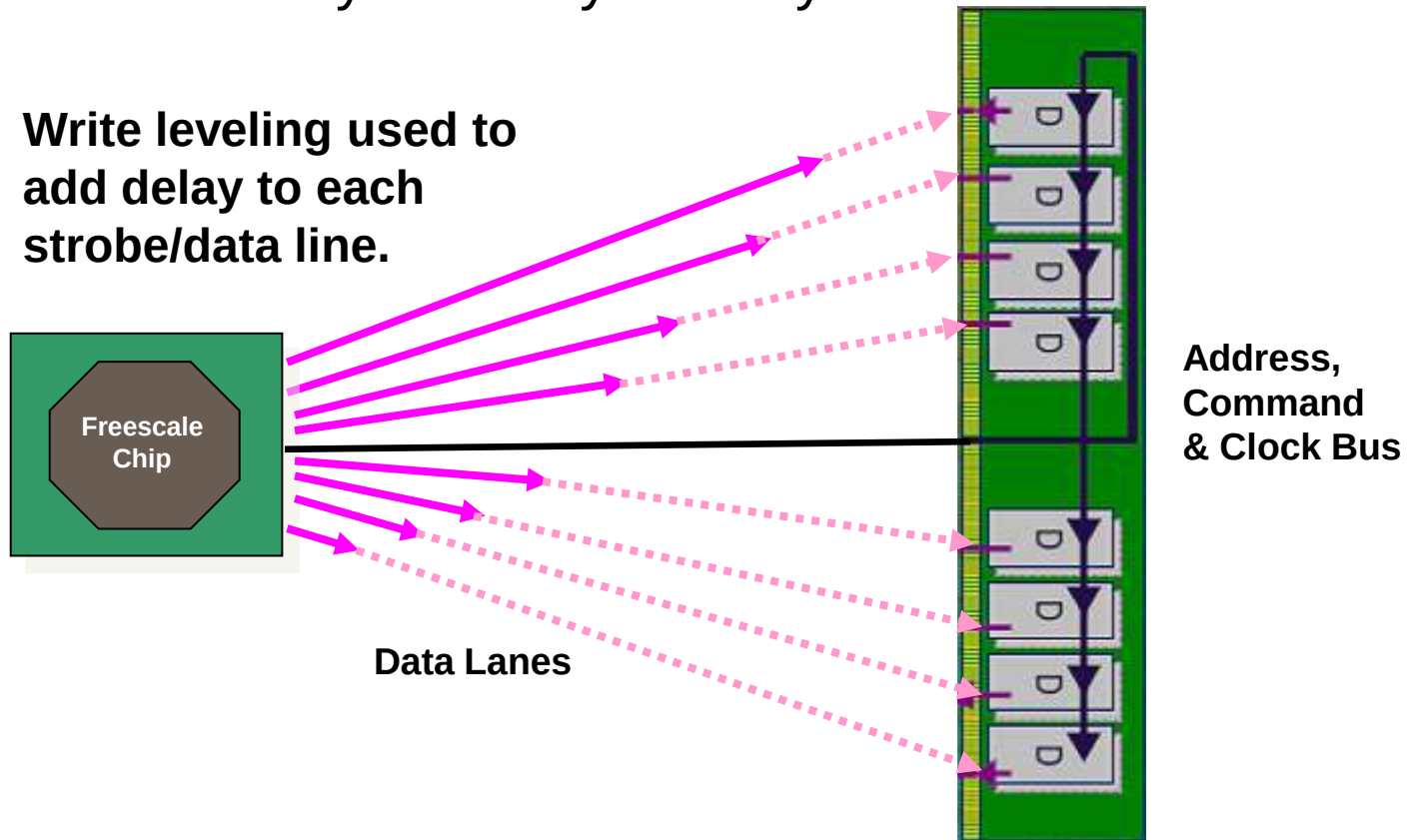
- **Automatic CAS to preamble calibration**
- **Data strobe to data skew adjustment**



Write Adjustment

- Write leveling sequence during the initialization process will determine the appropriate delays to each strobe/data byte lane and add this delay for every write cycle

- **Write leveling used to add delay to each strobe/data line.**



DDR3L support

- DDR3L (1.35V) is a low voltage version of the DDR3 (1.5V)
- DDR3L meets the exact same functional and timing specifications of DDR3
- VIH/VIL differences are compensated by corresponding derating values to Vref resulting in no change in AC timing, and timing budget calculation
- The main considerations for using DDR3L are:
 - Memory controller needs to support DDR3L
 - P1023, P1017, P1010, P1014, P2040, P3041, P5020
 - The supply voltage needs to be at 1.35V
 - Using DDR3L SDRAM

Register Configuration

- Two general type of registers to be configured in the memory controller
- First register type is set to the DRAM related parameter values that are provided via SPD or DRAM datasheet
- Second register type is the non-SPD values that are set based on the specific application. For example:
 - On-die-termination (ODT) settings for DRAM and controller
 - Driver impedance setting for DRAM and controller
 - Clock adjust, write data delay, Cast to preamble override (CPO)
 - 2T or 3T timing
 - Burst type selection (fixed or on-the-fly burst chop mode)
 - Write-leveling start value (WRLVL_START)
- Freescale's Processor Expert QorIQ Configuration Suite includes a DDR configuration tool for many devices. For other devices, Freescale support resources can help generate or analyze DDR settings.

DDR3 SDRAM

Summary



- DDR3/DDR3L is mainstream now
- DDR4 is expected to start entering the market by 2013
- All QorIQ devices support DDR3
- All features of DDR3, such as write leveling, ZQ calibration, ODT, Mirrored DIMM, ... are supported by the memory controller in QorIQ devices
- Follow JEDEC recommended topologies for discrete parts
- Configuration and initialization of memory controller is easily achieved

- Books:

- 



DDR Configuration and Validation Tools



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QorlQ Configuration Suite – Now Available!

- **QorIQ Configuration Suite v2.3 is NOW AVAILABLE!!!**
 - Supports all QorIQ and Qorivva devices
 - Works with Eclipse 3.5, Eclipse 3.6, Eclipse 3.7 development tools
 - Pure Java solution for maximum choice of host system support
 - Add-in to CodeWarrior Development Studio for PA, v10.1 or later
 - Available from www.freescale.com/QCS – FREE DOWNLOAD*
- **Includes the following four configuration tools all designed to collaborate on consistent configuration:**
 - PBL tool to define the Reset Control Word bit values and PBI data for the pre-boot
 - BOOTROM generator for those QorIQ without RCW functionality
 - DDR configuration supports setting the controller to a working state for any DDR
 - Data path graphical view helps to define data path configuration for the DPAA.
 - Hardware Device Tree editor supports references, synchronous GUI and XML editing, node validation based on specification bindings
 - Packaged as a separate product with installer and wizard functionality

* Must be a QorIQ customer or under QorIQ NDA for download permission

Actual URL is http://www.freescale.com/webapp/sps/site/prod_summary.jsp?code=PE_QORIQ_SUITE&tid=PEH

Installing Processor Expert for QorIQ

- You need CodeWarrior for PA 10.1 or later

OR, you download an Eclipse version for free

OR, you use an existing Eclipse workbench you have installed (Wind River, QNX, GNU, etc.)

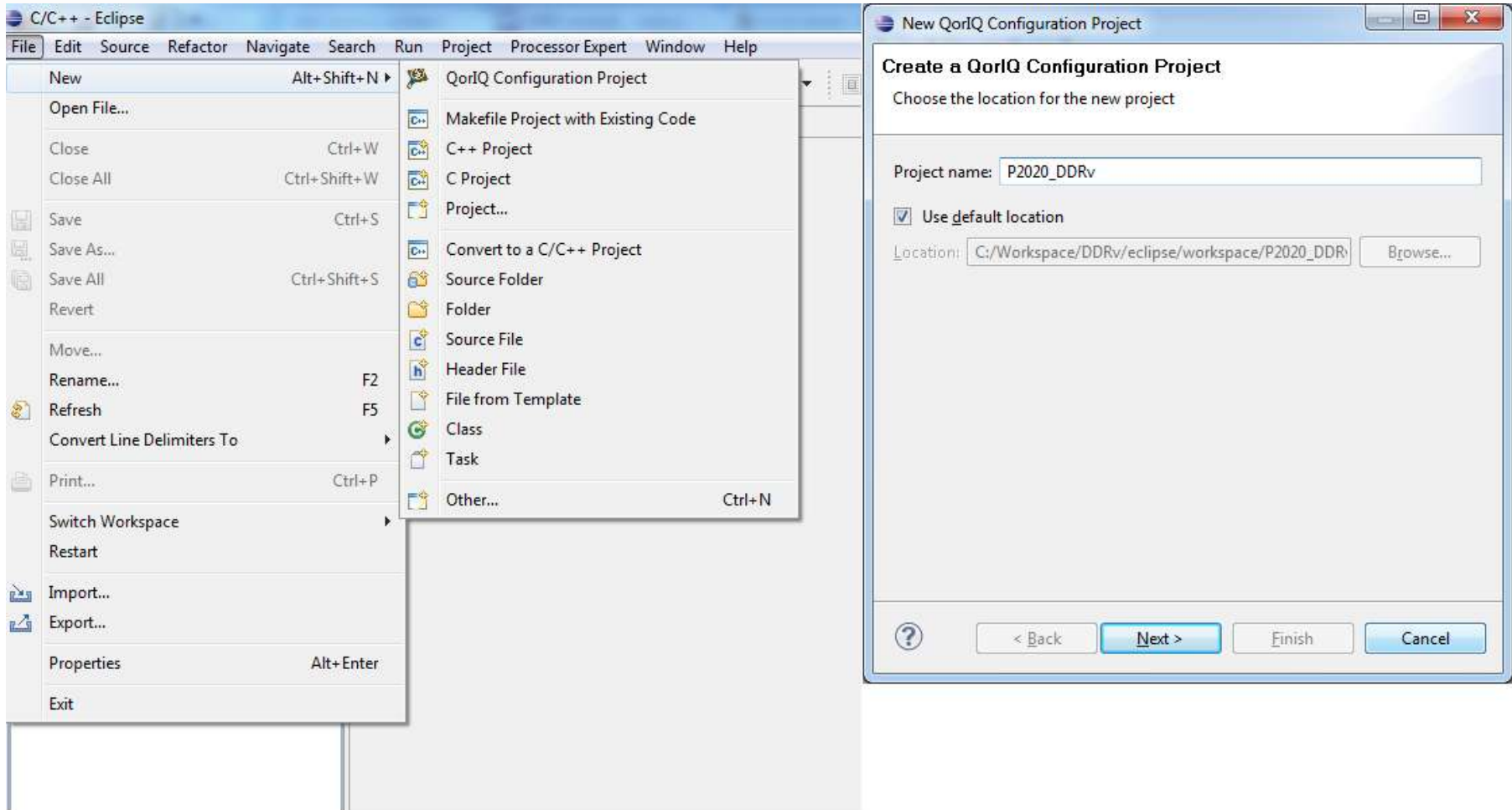
- Processor Expert for QorIQ Configuration Suite installs using the Eclipse updater's "Add new software..." capability
- The Configuration Suite is 100% pure Java so it should run on any Eclipse 3.6.1 or later host environment (Windows, Linux, Solaris, Mac OS, 32-bit/64-bit, ...)

DDR Configuration

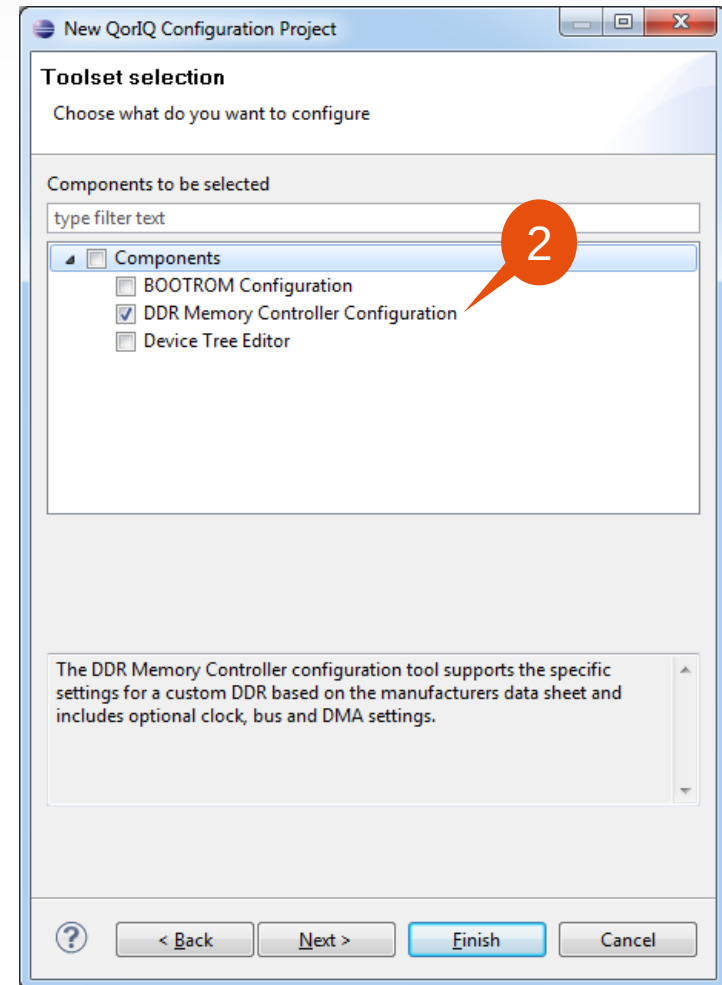
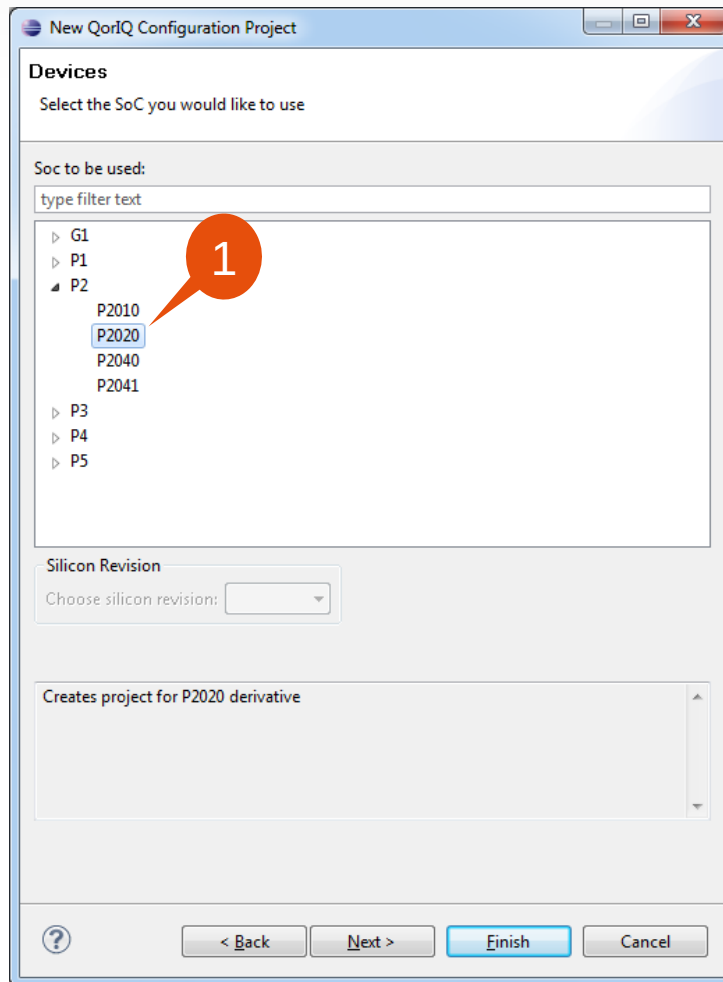
Lab: Creating New DDR Configuration



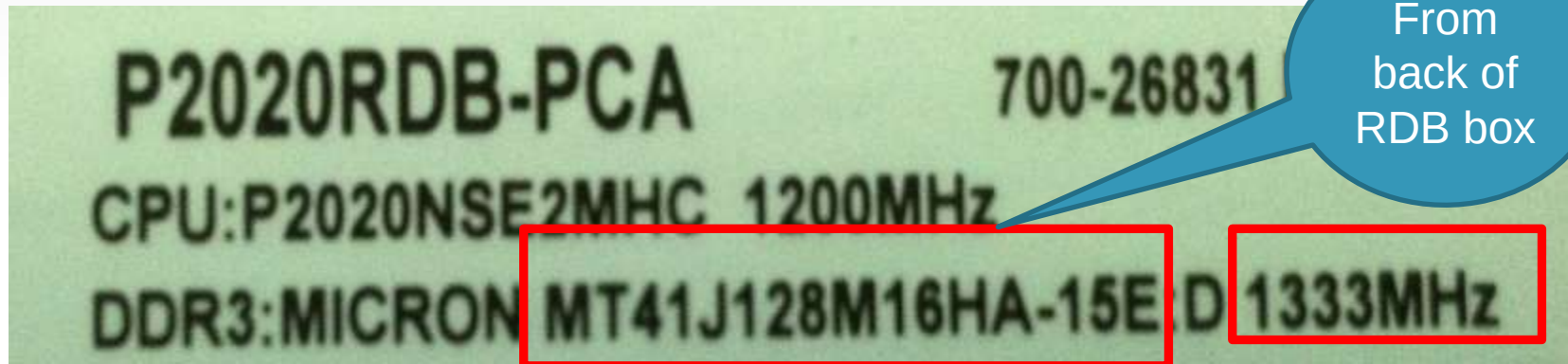
Create New QCS project



Select device and DDR component



Get DRAM information – P2020RDB-PCA



From
back of
RDB box



DDR3 SDRAM

MT41J512M4 – 64 Meg x 4 x 8 Banks

MT41J256M8 – 32 Meg x 8 x 8 Banks

MT41J128M16 – 16 Meg x 16 x 8 Banks

From DRAM datasheet

Speed Grade	Data Rate (MT/s)	Target ^t RCD- ^t RP-CL	^t RCD (ns)	^t RP (ns)	CL (ns)
-093 ^{1, 2, 3, 4}	2133	14-14-14	13.09	13.09	13.09
-107 ^{1, 2, 3}	1866	13-13-13	13.91	13.91	13.91
-125 ^{1, 2}	1600	11-11-11	13.75	13.75	13.75
-15E ¹	1333	9-9-9	13.5	13.5	13.5
-187E	1066	7-7-7	13.1	13.1	13.1

- Tool automatically computes tRCD, tRP, and CL!
 - User can change these values if required.

- $V_{DD} = V_{DDQ} = 1.5V \pm 0.075V$
- 1.5V center-terminated push/pull I/O
- Differential bidirectional data strobe
- 8n-bit prefetch architecture
- Differential clock inputs (CK, CK#)
- 8 internal banks
- Nominal and dynamic on-die termination (ODT) for data, strobe, and mask signals
- Programmable CAS READ latency (CL)
- Posted CAS additive latency (AL)
- Programmable CAS WRITE latency (CWL) based on t_{CK}
- Fixed burst length (BL) of 8 and burst chop (BC) of 4 (via the mode register set [MRS])
- Selectable BC4 or BL8 on-the-fly (OTF)
- Self refresh mode
- T_C of 0°C to 95°C
 - 64ms, 8192 cycle refresh at 0°C to 85°C
 - 32ms, 8192 cycle refresh at 85°C to 95°C
- Self refresh temperature (SRT)
- Write leveling
- Multipurpose register
- Output driver calibration

- Configuration
 - 512 Meg x 4
 - 256 Meg x 8
 - 128 Meg x 16
- FBGA package (Pb-free) - x4, x8
 - 78-ball (8mm x 10.5mm) Rev. H,M,J,K
 - 78-ball (9mm x 11.5mm) Rev. D
- FBGA package (Pb-free) - x16
 - 96-ball (9mm x 14mm) Rev. D
 - 96-ball (8mm x 14mm) Rev. K
- Timing - cycle time
 - 938ps @ CL = 14 (DDR3-2133)
 - 1.071ns @ CL = 13 (DDR3-1866)
 - 1.25ns @ CL = 11 (DDR3-1600)
 - 1.5ns @ CL = 9 (DDR3-1333)
 - 1.87ns @ CL = 7 (DDR3-1066)
- Operating temperature
 - Commercial (0°C ≤ T_C ≤ +95°C)
 - Industrial (-40°C ≤ T_C ≤ +95°C)
- Revision

512M4
256M8
128M16

DA
HX

HA
JT

-093
-107
-125
-15E
-187E

None
IT
:D/:H/:J/:K/
:M

DDR New Project Wizard

New QorIQ Configuration Project

DDR Configuration

Configured device P2020

Configure: 1st DDR Controller

Configuration mode

- ☒ Auto configuration
- ☐ Import from memory file
- ☒ Discrete DRAM
- ☐ DRAM Module

DDR Controller

Type: DDR 3

Data Rate: 800 MT/s

Ranks: 1

Data Bus width: 64 bits

CAS# Latency (tCL): 6 clocks

tRP/tRCD: 13.5 ns

☐ ECC Enabled

DRAM Settings

DRAM Configuration per Rank: 1Gb: 128Mb x8

DRAM Speed Rating: 1333 MT/s

Select 1st DDR Controller

? < Back Next > Finish Cancel

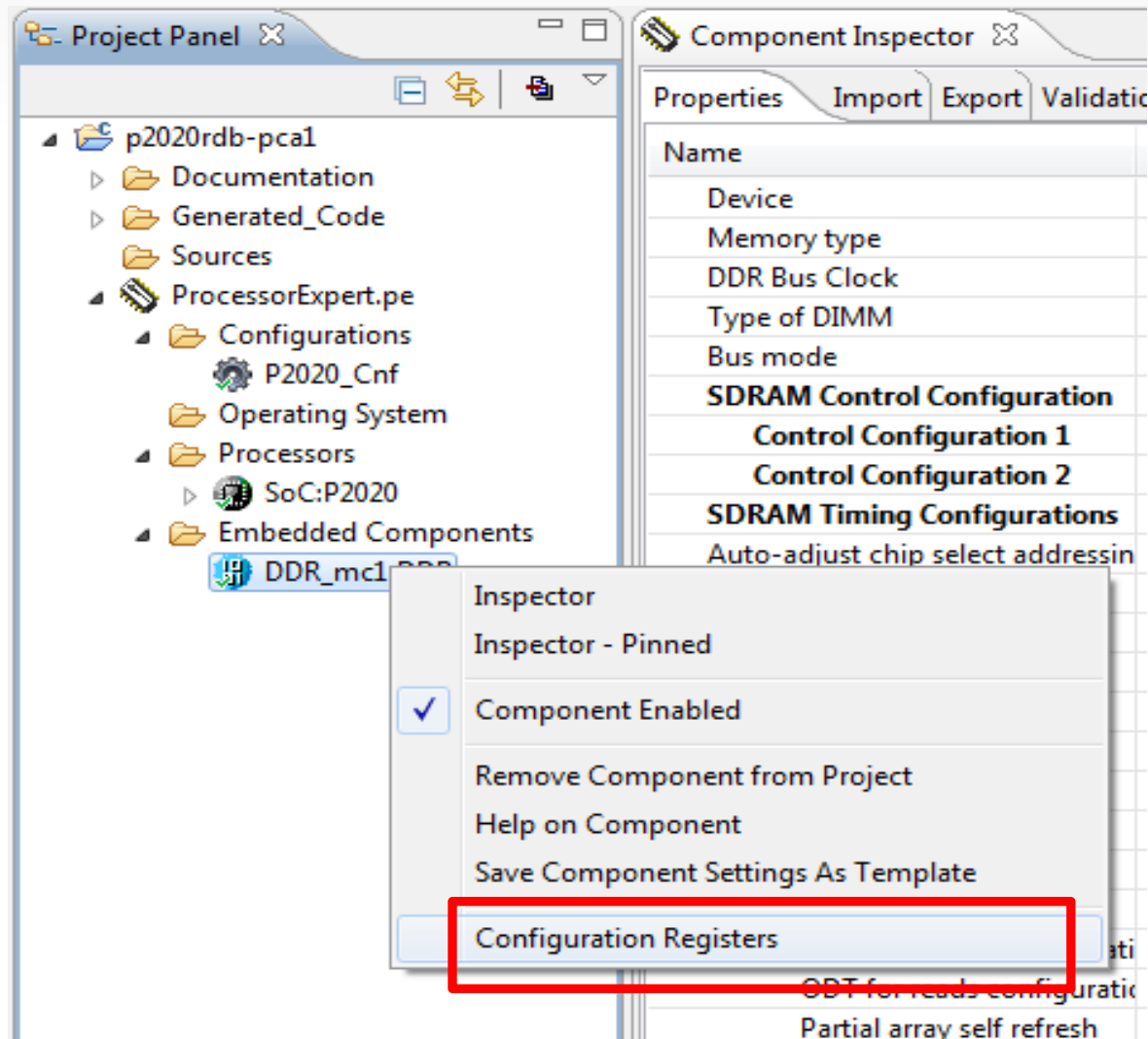
- From memory data sheet:
 - Maximum speed rating
 - Capacity

QCS project explorer

The screenshot displays two windows from a software development environment. The 'Project Panel' on the left shows a project tree for 'p2020rdb-pca1'. Under 'Embedded Components', the component 'DDR_mc1:DDR' is selected and highlighted with a red rectangular box. The 'Component Inspector' window on the right shows the configuration for the selected component, 'DDR_Controller_1'. It features a table with three columns: 'Name', 'Value', and 'Details'. The table lists various properties such as 'Device', 'Memory type', 'DDR Bus Clock', and 'Type of DIMM'. It also includes expandable sections for 'SDRAM Control Configuration' and 'SDRAM Timing Configurations', which contain further sub-properties like 'Auto-adjust chip select addressing', 'Chip Select 0', 'Memory Bounds', and 'Configuration'.

Name	Value	Details
Device	DDR_Controller_1	DDR_Controller_1
Memory type	DDR 3	
DDR Bus Clock	400 MHz	DDR Data Rate: 800 MT/s
Type of DIMM	Unbuffered DIMMs	
Bus mode	64-bit bus	
SDRAM Control Configuration		
Control Configuration 1		
Control Configuration 2		
SDRAM Timing Configurations		
Auto-adjust chip select addressing	yes	
Chip Select 0	Enabled	
Memory Bounds		
Start Address	0	
Size	1 GB	
Configuration		
Auto Precharge Always	no	
Internal Banks Number	8 internal banks	
Number of row bits	14 row bits	
Number of column bits	10 column bits	
ODT for writes configuration	Assert ODT only during writes to C...	
ODT for reads configuration	Never assert ODT for reads	
Partial array self refresh	Full Array	
Chip Select 1	Disabled	
Chip Select 2	Disabled	
Chip Select 3	Disabled	

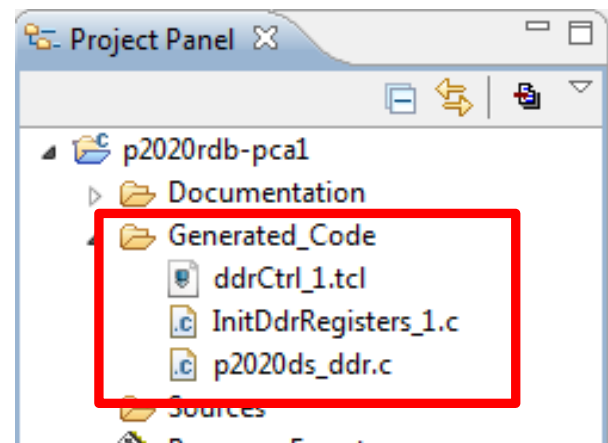
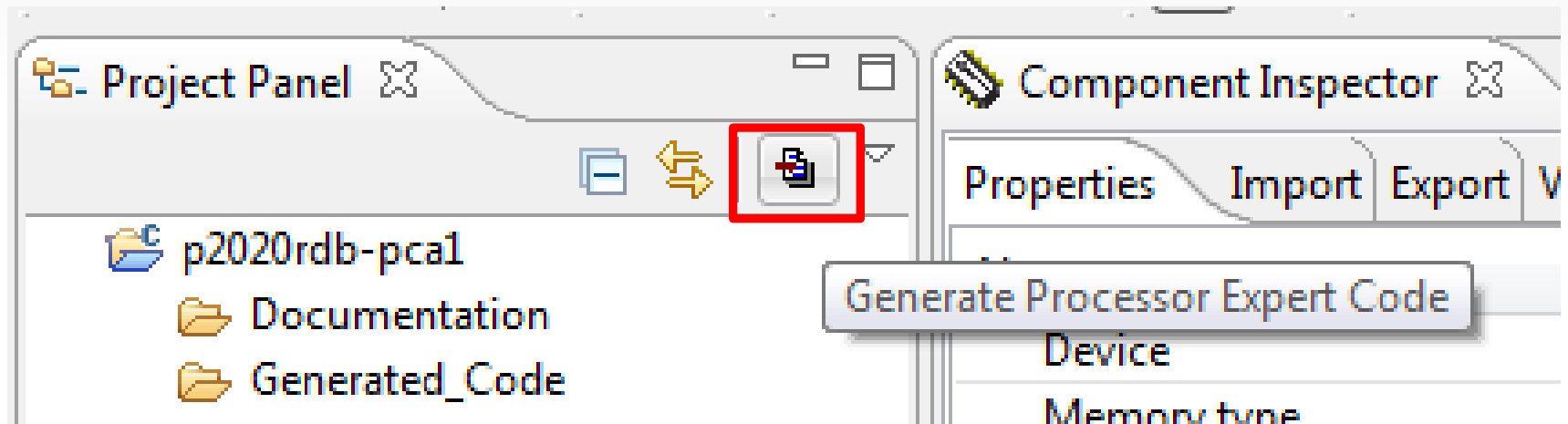
Review DDR registers values



Review DDR registers values – contd.

Reg. name	Init. value	After reset
Peripheral registers		
▶ DDR1_CS0_BNDS	0000003F	00000000
▶ DDR1_CS1_BNDS	00000000	00000000
▶ DDR1_CS2_BNDS	00000000	00000000
▶ DDR1_CS3_BNDS	00000000	00000000
▶ DDR1_CS0_CONFIG	80014202	00000000
▶ DDR1_CS1_CONFIG	00000000	00000000
▶ DDR1_CS2_CONFIG	00000000	00000000
▶ DDR1_CS3_CONFIG	00000000	00000000
▶ DDR1_CS0_CONFIG_2	00000000	00000000
▶ DDR1_CS1_CONFIG_2	00000000	00000000
▶ DDR1_CS2_CONFIG_2	00000000	00000000
▶ DDR1_CS3_CONFIG_2	00000000	00000000
▶ DDR1_TIMING_CFG_3	00030000	00000000
▶ DDR1_TIMING_CFG_0	00330104	00110105
▶ DDR1_TIMING_CFG_1	6E6B8846	00000000
▶ DDR1_TIMING_CFG_2	0FA8D0CC	00000000
▶ DDR1_SDRAM_CFG	47000008	03000000
▶ DDR1_SDRAM_CFG_2	24401050	00000000
▶ DDR1_SDRAM_MODE	00061421	00000000

Generate DDR configuration



Generated files – CW, uboot, ddrinit.c

```
# DDR Controller 1 Registers

# DDR_SDRAM_CFG
mem [0xFF702110] = 0x47000008

# CS0_BNDS
mem [0xFF702000] = 0x3F

# CS0_CONFIG
mem [0xFF702080] = 0x80014202

# CS0_CONFIG_2
mem [0xFF7020C0] = 0x00

# TIMING_CFG_3
mem [0xFF702100] = 0x00030000

# TIMING_CFG_0
mem [0xFF702104] = 0x00330104

# TIMING_CFG_1
mem [0xFF702108] = 0x6E6B8846

# TIMING_CFG_2
mem [0xFF70210C] = 0x0FA8D0CC

# DDR_SDRAM_CFG_2
mem [0xFF702114] = 0x24401050

# DDR_SDRAM_MODE
mem [0xFF702118] = 0x00061421
```

```
#define DDR_1_INIT_EXT_ADDR_ADDR 0xFF70214C
#define DDR_1_SDRAM_RCW_1_ADDR 0xFF702180
#define DDR_1_SDRAM_RCW_2_ADDR 0xFF702184
#define DDR_1_DATA_INIT_ADDR 0xFF702128
#define DDR_1_SDRAM_MD_CNTL_ADDR 0xFF702120
#define DDR_1_DDRCDR_1_ADDR 0xFF702B28
#define DDR_1_DDRCDR_2_ADDR 0xFF702B2C

#define SDRAM_CFG_MEM_EN_MASK 0x80000000
#define SDRAM_CFG2_D_INIT_MASK 0x00000010

/* DDR Controller configured registers' values */
#define DDR_1_CS0_BNDS_VAL 0x3F
#define DDR_1_CS1_BNDS_VAL 0x00
#define DDR_1_CS2_BNDS_VAL 0x00
#define DDR_1_CS3_BNDS_VAL 0x00
#define DDR_1_CS0_CONFIG_VAL 0x80014202
#define DDR_1_CS1_CONFIG_VAL 0x00
```

```
#define PEX_CONFIG_DDR1_INIT_EXT_ADDR 0x00000000
#define PEX_CONFIG_DDR1_TIMING_4 0x00220001
#define PEX_CONFIG_DDR1_TIMING_5 0x02401400
#define PEX_CONFIG_DDR1_ZQ_CNTL 0x89080600
#define PEX_CONFIG_DDR1_WRLVL_CNTL 0x8655F614
#define PEX_CONFIG_DDR1_RCW_1 0x00000000
#define PEX_CONFIG_DDR1_RCW_2 0x00000000

/* DDR Controller 1 configuration global structures */
fsl_ddr_cfg_regs_t ddr_cfg_regs_0 = {
    .cs[0].bnds = PEX_CONFIG_DDR1_CS0_BNDS,
    .cs[1].bnds = PEX_CONFIG_DDR1_CS1_BNDS,
    .cs[2].bnds = PEX_CONFIG_DDR1_CS2_BNDS,
    .cs[3].bnds = PEX_CONFIG_DDR1_CS3_BNDS,
    .cs[0].config = PEX_CONFIG_DDR1_CS0_CONFIG,
    .cs[1].config = PEX_CONFIG_DDR1_CS1_CONFIG,
    .cs[2].config = PEX_CONFIG_DDR1_CS2_CONFIG,
```

Steps to adapt DDR configuration file in CodeWarrior

- Open the CW config file you want to adapt

D:\Program Files\Freescale\CW PA
v10.1\PA\PA_Support\Initialization_Files\QorIQ_P4\
P4080DS_init_core0.cfg

- Replace DDR1 config section with the one from

D:\Profiles\b08844\workspace\p4080\Generated_Code\
ddrCtrl_1.cfg

- Use this new config file with your stationary project

DDR Validation Tool



DDR Validation Tool - Activate

The screenshot displays the 'Project Panel' on the left and the 'Component Inspector' on the right. In the Project Panel, the 'p2020rdb-pca1' project is expanded, showing folders for 'Documentation', 'Generated_Code', 'Sources', and 'ProcessorExpert.pe'. Under 'ProcessorExpert.pe', there are 'Configurations' (including 'P2020_Cnf'), 'Operating System', 'Processors' (including 'SoC:P2020'), and 'Embedded Components'. The 'DDR_mc1:DDR' component is selected under 'Embedded Components'.

The Component Inspector shows the 'Validation' tab, which displays a table of properties for the selected component. The table has three columns: 'Name', 'Value', and 'Details'.

Name	Value	Details
Device	DDR_Controller_1	DDR_Controller_1
Memory type	DDR 3	
DDR Bus Clock	400 MHz	DDR Data Rate: 800 MT/s
Type of DIMM	Unbuffered DIMMs	
Bus mode	64-bit bus	
SDRAM Control Configuration		
Control Configuration 1		
Control Configuration 2		
SDRAM Timing Configurations		
Auto-adjust chip select addressing	yes	
Chip Select 0	Enabled	
Memory Bounds		
Start Address	0	
Size	1 GB	
Configuration		
Auto Precharge Always	no	
Internal Banks Number	8 internal banks	
Number of row bits	14 row bits	
Number of column bits	10 column bits	
ODT for writes configuration	Assert ODT only during writes to C...	
ODT for reads configuration	Never assert ODT for reads	
Partial array self refresh	Full Array	
Chip Select 1	Disabled	
Chip Select 2	Disabled	
Chip Select 3	Disabled	

License file:
<QCS Install directory>/eclipse/Optimization/license.dat



DDRv Basic Connection Test

[illegible]

- Run basic test to confirm target connection

Configure DDR scenarios and tests

The screenshot shows the 'Component Inspector' application window. The 'Validation' tab is selected in the top navigation bar. On the left, under the 'Test' column, a tree view shows 'Validation' expanded, with 'Centering the clock' selected and checked. A red circle with the number '1' points to this selection. Below this, the 'Choose validation mode:' dropdown is set to 'In depth'. A 'Start Validation' button is visible. At the bottom, the 'Connection settings' section shows 'System: P2020; USBTAP id:' with a link icon. On the right, the 'Choose tests' tab is active, displaying a table with the following data:

Test	Run times
☐ BIST Write Read Compare	0
☒ Read Write Compare	3
☐ Walking Ones	0
☐ Walking Zeros	0

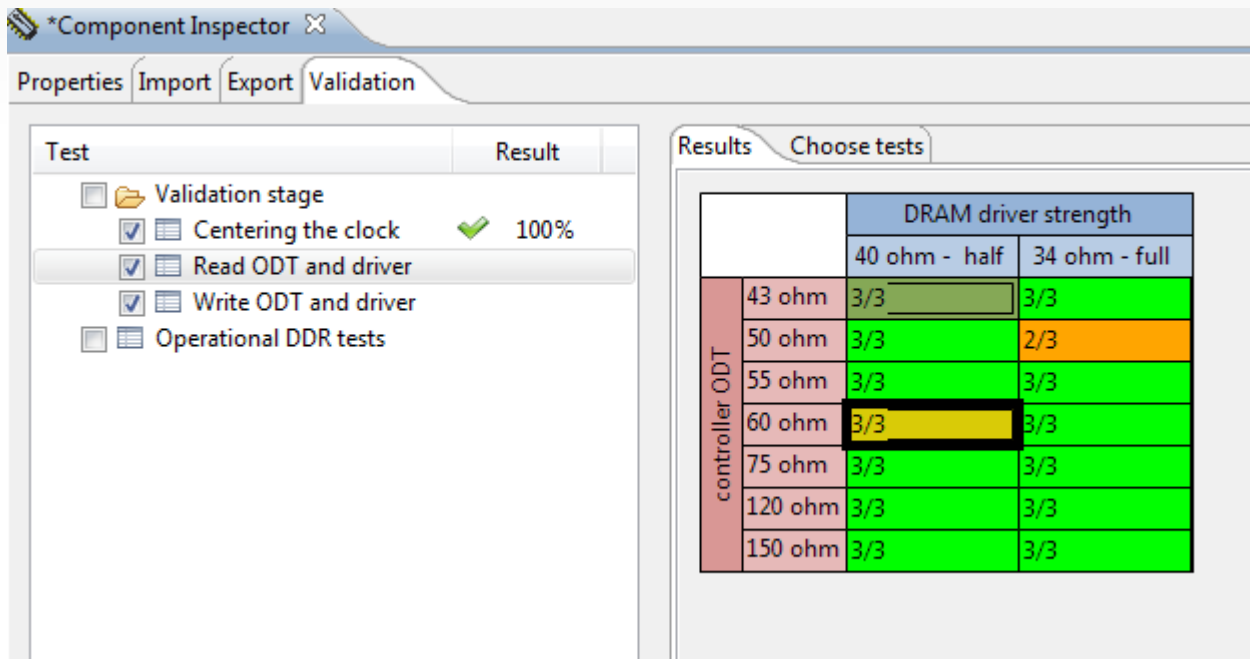
A red circle with the number '2' points to the 'Read Write Compare' row in the table. The 'Results' tab is also visible on the right, with the text 'Select what test to run per each cell and how many times:'.

Centering of the clock results

[illegible]

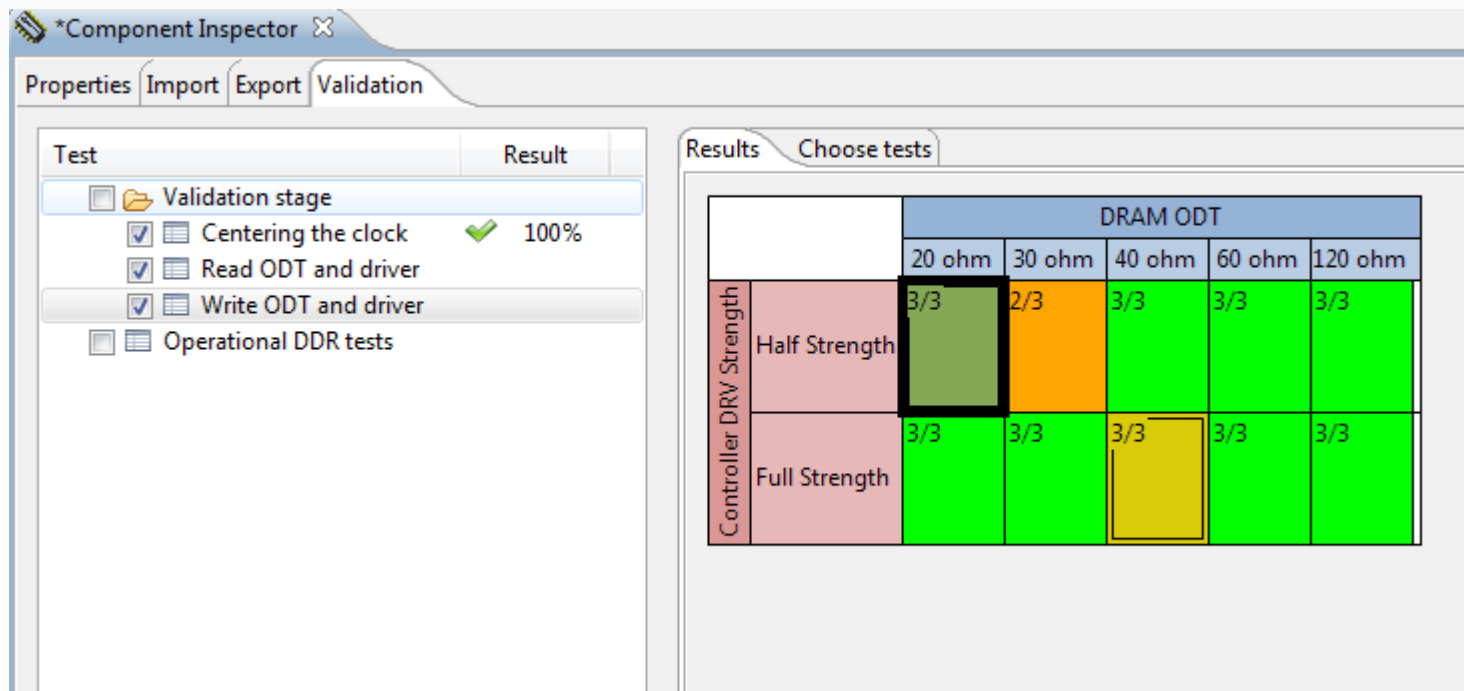
- Click “cell” to choose Write level start and CLK_ADJ values.

DDR read ODT and driver strength – test results



- Click “cell” to choose optimized ODT value.

DDR write ODT and drive strength – test results



- Click “cell” to choose optimized ODT value.

Centering of the clock - after ODT optimization

Results Choose tests

		CLK_ADJ								
		0 clocks	1/8 clocks	1/4 clocks	3/8 clocks	1/2 clocks	5/8 clocks	3/4 clocks	7/8 clocks	1 clocks
WRLVL_START	0 clock delay	0/3	3/3	0/3	0/3	0/3	0/3	0/3	0/3	0/3
	1/8 clock delay	0/3	3/3	3/3	3/3	0/3	0/3	0/3	0/3	0/3
	1/4 clock delay	0/3	3/3	3/3	3/3	0/3	0/3	0/3	0/3	0/3
	3/8 clock delay	0/3	3/3	3/3	3/3	3/3	3/3	0/3	0/3	0/3
	1/2 clock delay	0/3	3/3	3/3	3/3	3/3	3/3	0/3	0/3	0/3
	5/8 clock delay	0/3	3/3	3/3	3/3	3/3	3/3	3/3	3/3	0/3
	3/4 clock delay	0/3	0/3	3/3	3/3	3/3	3/3	3/3	3/3	0/3
	7/8 clock delay	0/3	0/3	0/3	3/3	3/3	3/3	2/3	3/3	0/3
	1 clock delay	0/3	0/3	0/3	0/3	3/3	3/3	3/3	3/3	0/3
	9/8 clock delay	0/3	0/3	0/3	0/3	0/3	3/3	3/3	3/3	0/3
	5/4 clock delay	0/3	0/3	0/3	0/3	0/3	0/3	2/3	3/3	0/3
	11/8 clock delay	0/3	0/3	0/3	0/3	0/3	0/3	0/3	3/3	0/3
	3/2 clock delay	0/3	0/3	0/3	0/3	0/3	0/3	0/3	0/3	0/3
	13/8 clock delay	0/3	0/3	0/3	0/3	0/3	0/3	0/3	0/3	0/3
	7/4 clock delay	0/3	0/3	0/3	0/3	0/3	0/3	0/3	0/3	0/3
	15/8 clock delay	0/3	3/3	0/3	0/3	0/3	0/3	0/3	0/3	0/3
	2 clock delay	0/3	3/3	0/3	0/3	0/3	0/3	0/3	0/3	0/3
	17/8 clock delay	0/3	3/3	3/3	3/3	0/3	0/3	0/3	0/3	0/3
	9/4 clock delay	0/3	3/3	3/3	3/3	0/3	0/3	0/3	0/3	0/3
	19/8 clock delay	0/3	3/3	3/3	3/3	3/3	3/3	0/3	0/3	0/3
	5/2 clock delay	0/3	3/3	3/3	3/3	3/3	3/3	0/3	0/3	0/3

- Centering of clock scenario was re-run after finding the right ODT values

Generate optimized DDR configuration

The screenshot displays the IDE's Project Panel and Component Inspector. In the Project Panel, the 'p2020rdb-pca1' project is expanded, showing folders for Documentation, Generated_Code, Sources, and ProcessorExpert.pe. Under ProcessorExpert.pe, the 'Configurations' folder contains 'P2020_Cnf', and the 'Processors' folder contains 'SoC:P2020'. The 'Embedded Components' folder is expanded, and 'DDR_mc1:DDR' is selected. The Component Inspector on the right shows the 'Validation' tab for the 'DDR_Controller_1' component. The table lists properties such as Device (DDR_Controller_1), Memory type (DDR 3), DDR Bus Clock (400 MHz), Type of DIMM (Unbuffered DIMMs), Bus mode (64-bit bus), SDRAM Control Configuration (Control Configuration 1, Control Configuration 2), SDRAM Timing Configurations (Auto-adjust chip select addressing: yes), Chip Select 0 (Enabled), Memory Bounds (Start Address: 0, Size: 1 GB), Configuration (Auto Precharge Always: no, Internal Banks Number: 8 internal banks, Number of row bits: 14 row bits, Number of column bits: 10 column bits, ODT for writes configuration: Assert ODT only during writes to C..., ODT for reads configuration: Never assert ODT for reads, Partial array self refresh: Full Array), and Chip Select 1, 2, and 3 (all Disabled).

Name	Value	Details
Device	DDR_Controller_1	DDR_Controller_1
Memory type	DDR 3	
DDR Bus Clock	400 MHz	DDR Data Rate: 800 MT/s
Type of DIMM	Unbuffered DIMMs	
Bus mode	64-bit bus	
SDRAM Control Configuration		
Control Configuration 1		
Control Configuration 2		
SDRAM Timing Configurations		
Auto-adjust chip select addressing	yes	
Chip Select 0	Enabled	
Memory Bounds		
Start Address	0	
Size	1 GB	
Configuration		
Auto Precharge Always	no	
Internal Banks Number	8 internal banks	
Number of row bits	14 row bits	
Number of column bits	10 column bits	
ODT for writes configuration	Assert ODT only during writes to C...	
ODT for reads configuration	Never assert ODT for reads	
Partial array self refresh	Full Array	
Chip Select 1	Disabled	
Chip Select 2	Disabled	
Chip Select 3	Disabled	

Pricing \$995

License file:

```
<QCS Install directory>/eclipse/Optimization/license.dat
```

-
- *Component Inspector
- Basic Advanced Expert
- Properties Import Export Validation
- Memory Dump File
- Input File C:\Users\r00086\Desktop\p2020ddrv_ubootdump.txt Browse...
- File Format U-Boot Dump
- Addressable Size 1 byte
- Endianness Big Endian (default)
- Address Information
- Beginning memory address read from memory dump file
- DDR Controller memory address ff702000 ☒ Use default
- Import

Processor Expert for QorIQ ... For More Info

- Freescale's Processor Expert landing page
 - http://www.freescale.com/webapp/sps/site/prod_summary.jsp?code=PROCESSOR-EXPERT&tid=PEH
 - <http://www.processorexpert.com/>
- QorIQ Configuration Suite
 - http://www.freescale.com/webapp/sps/site/prod_summary.jsp?code=PE_QORIQ_SUITE&tid=PEH
- QorIQ Optimization Suite
 - http://www.freescale.com/webapp/sps/site/prod_summary.jsp?code=PE_QORIQ_OPTI_SUITE&tid=PEH
- Freescale Component Store – purchasing embedded software
 - http://www.freescale.com/webapp/sps/site/homepage.jsp?code=BEAN_STORE_MAIN&tid=SWnT

Pricing & Availability

- Part numbers : CWA-QIQ-OPTP-FL (floating license) & CWA-QIQ-OPTP-NL (node locked)
- Price : \$999 Annual Subscription
- License Duration : 1 year
- Support & Maintenance : Included
- Availability
 - Scenarios Tool – Now
 - DDRv – Now

